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TIDA-00461 REV E1 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	C1, C4	2	150pF	GRM1555C1H151JA01D	MuRata	CAP. CERM, 150 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
2	C2	1	1uF	CGA4J3X7S2A105K125AB	TDK	CAP, CERM, 1 uF, 100 V, +/- 10%, X7S, AEC-Q200 Grade 1, 0805	0805
3	C3, C6	2	1uF	GRM155R61A105KE15D	MuRata	CAP, CERM, 1 uF, 10 V, +/- 10%, X5R, 0402	0402
4	C5, C7	2	0.1uF	GRM155R71C104JA88D	MuRata	CAP, CERM, 0.1 uF, 16 V, +/- 5%, X7R, 0402	0402
5	C9, C10	2	10pF	GRM1555C1H100RA01D	MuRata	CAP, CERM, 10 pF, 50 V, +/- 4%, C0G/NP0, 0402	0402
6	D2	1	Rgb	SMLP36RGB2W3	Rohm	LED, Rgb, SMD	1.5x1mm
7	D3, D4, D5	3	Green	150060VS75000	Würth Elektronik	LED, Green, SMD	LED_0603
8	FID1, FID2, FID3	3		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	N/A
9	H1, H2, H3, H4	4		NY PMS 440 0025 PH	B&F Fastener Supply	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw
10	H5, H6, H7, H8	4		1902C	Keystone	Standoff, Hex, 0.5"L #4-40 Nylon	Standoff
11	H9	1		1803578	Phoenix Contact	Terminal Block Plug, 3.81mm, 2x1, Green	
12	J1	1				M12 Socket, Backmounting, 4Pos, Gold, R/A, TH	
13	J2, J13	2		61300311121	Würth Elektronik	Header, 2.54 mm, 3x1, Gold, TH	Header, 2.54mm, 3x1, TH
14	J3, J4	2		61300211121	Würth Elektronik	Header, 2.54 mm, 2x1, Gold, TH	Header, 2.54mm, 2x1, TH
15	J11, J12	2		61301011121	Würth Elektronik	Header, 2.54mm, 10x1, Gold, TH	Header, 2.54mm, 10x1, TH
16	J14	1		612 014 217 21	Würth Elektronik	Header (Shrouded), 2.54 mm, 7x2, Gold, R/A, TH	Header, 2.54 mm, 7x2, R/A, TH
17	J15	1		61300611121	Würth Elektronik	Header, 2.54 mm, 6x1, Gold, TH	Header, 2.54mm, 6x1, TH
18	LBL1	1		THT-14-423-10	Brady	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650 x 0.200 inch
19	R1, R2	2	10.0k	CRCW020110K0FKED	Vishay-Dale	RES, 10.0 k, 1%, 0.05 W, 0201	0201
20	R3	1	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0, 5%, 0.063 W, 0402	0402
21	R7, R8	2	140	CRCW0402140RFKED	Vishay-Dale	RES, 140, 1%, 0.063 W, 0402	0402
22	R9	1	499	CRCW0402499RFKED	Vishay-Dale	RES, 499, 1%, 0.063 W, 0402	0402
23	R11, R13, R14	3	68.1	CRCW040268R1FKED	Vishay-Dale	RES, 68.1, 1%, 0.063 W, 0402	0402
24	R12	1	47.5k	CRCW060347K5FKEA	Vishay-Dale	RES, 47.5 k, 1%, 0.1 W, 0603	0603
25	S1, S2	2		434121025816	Würth Elektronik	Switch, Tactile, SPST, 12 V, SMD	SMD, 6x3.9mm
26	SH-J3, SH-J13	2		60900213421	Würth Elektronik	Shunt, 2.54mm, Gold, Black	Shunt, 2.54mm, Black
27	U1	1		TIOL111	Texas Instruments	IO-Link Device Transceiver with Integrated Surge Protection, TIOL111 (WSON-10)	TIOL111
28	U2	1		MSP430FR5969IRGZR	Texas Instruments	MSP430FR5969 16 MHz Ultra-Low-Power Microcontroller featuring 64 KB FRAM, 2 KB SRAM, 40 IO, RGZ0048B (VQFN-48)	RGZ0048B
29	Y1	1		MS3V-T1R 32.768KHZ 7.0 PF	Micro Crystal AG	Crystal, 32.768 KHz, 7pF, SMD	1.4x1.4x5.0mm SMD
30	C8	0	100pF	GRM1885C1H101JA01D	MuRata	CAP, CERM, 100 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
31	C11	0	1000pF	885012205061	Würth Elektronik	CAP, CERM, 1000 pF, 50 V, +/- 10%, X7R, 0402	0402
32	D1	0	600V	MURS160-13-F	Diodes Inc.	Diode, Ultrafast, 600 V, 1 A, SMB	SMB
33	J5	0		1803277	Phoenix Contact	Terminal Block, 2x1, 3.81mm, R/A, TH	Connector, 2 pos. 3.8mm RA
34	J7, J8, J9, J10	0		61300211121	Würth Elektronik	Header, 2.54 mm, 2x1, Gold, TH	Header, 2.54mm, 2x1, TH
35	Q1	0	60V	DMN61D8L-7	Diodes Inc.	MOSFET, N-CH, 60 V, 0.47 A, AEC-Q101, SOT-23	SOT-23
36	R4	0	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0, 5%, 0.1 W, 0603	0603
37	R5	0	100k	CRCW0603100KFKEA	Vishay-Dale	RES, 100 k, 1%, 0.1 W, 0603	0603
38	R6	0	1.00k	CRCW06031K00FKEA	Vishay-Dale	RES, 1.00 k, 1%, 0.1 W, 0603	0603
39	R10	0	1.00	CRCW25121R00FNEG	Vishay-Dale	RES, 1.00, 1%, 1 W, AEC-Q200 Grade 0, 2512	2512
40	SH-J7, SH-J8, SH-J9	0		60900213421	Würth Elektronik	Shunt, 2.54mm, Gold, Black	Shunt, 2.54mm, Black

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